EAST Search History

Ref#	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
		(438/149.ccls. or 257/72.ccls.)	USPAT	OR	OFF	2008/03/09 07:43
L1	19	thin same film\$6 same transistor\$1 same backplane and polyimide same substrate and "345"/\$. ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/10 11:23
L2	1	thin same film\$6 same transistor\$1 same backplane and polyimide same substrate and "345"/\$. ccls. and passivation	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/10 11:25
S1	115	thin same film\$6 same transistor\$1 same backplane	USPAT	OR	OFF	2008/03/06 13:29
S2	153	thin same film\$6 same transistor\$1 same backplane and polyimide same substrate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/06 13:31
S3	5	thin same film\$6 same transistor\$1 same backplane and polyimide same substrate and first same passivation same layer	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/06
S4	10	thin same film\$6 same transistor\$1 same backplane and polyimide same substrate and passivation same layer	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/06 13:36
S5	6	thin same film\$6 same transistor\$1 same backplane and polyimide same substrate and passivation same layer and deposit\$6 and array\$6 and gate same electrode\$1	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/06

S6	6	thin same film\$6 same transistor\$1 same backplane and polyimide same substrate and passivation same layer and deposit\$6 and array\$6 and gate same electrode\$1 and insulat \$6	US-PGPUB; USPAT; FPRS; EPO; JPO; DEFWENT; IBM_TDB	OR	OFF	2008/03/06 13:40
S7	4	thin same film\$6 same transistor\$1 same backplane and polyimide same substrate and passivation same layer and deposit\$6 and gate same electrode\$1 and insulat \$6 and semiconduct\$6 same channel same layer\$6 and source\$6 same electrode\$1 and drain\$6 same electrode\$1 and contact\$6 same layer\$6 same layer\$6 same layer\$8	US-PGPUB; USPAT; FPFS; EPC, JPC; DEFWENT; IBM_TDB	OR	OFF	2008/03/06 13:43
S8	4	thin same film\$6 same transistor\$1 same backplane and polyimide same substrate and passivation same layer and deposit\$6 and garay\$6 and garesistane same electrode\$1 and insulat \$5 and semiconduct\$6 and channel same layer \$6 and source\$6 same electrode\$1 and drain \$6 same electrode\$1 and pad\$1 and pad\$1 and contact \$6 same layer\$6	US-PGPUB; USPAT; FPFS; EPC, JPC; DEFWENT; IBM_TDB	ÖR	OFF	2008/03/06 13:44

S9	4	thin same film\$6 same transistor\$1 same backplane and polyimide same substrate and passivation same layer and deposit\$6 and garay\$6 and gares same electrode\$1 and insulat \$6 and semiconduct\$6 and semiconduct\$6 and semiconduct\$6 and semiconduct\$6 and semiconduct\$6 and channel same layer \$6 and source\$6 same electrode\$1 and drain \$6 same electrode\$1 and pad\$1 and contact \$6	US PEPUB; USPAT; FPTB; EPO; JPO; DEFWENT; IBM_TDB	OR	OFF	2008/03/06
S10	7	thin same film\$6 same transistor\$1 same backplane and polyimide same substrate and deposit \$6 and array\$6 and gate same electrode\$1 and insulat\$6 and semiconduct\$6 and channel same layer\$6 and source\$6 same electrode\$1 and frain \$6 same electrode\$1 and pad\$1 and contact \$6	US PGPUB; USPAT; FPRS; EPO; JPO; DEFWMENT; IBM_TDB	OR	OFF	2008/03/06 15:09
S11	8	thin same film\$6 same transistor\$1 same backplane and deposit \$6 and array\$6 and gate same electrode\$1 and insulat\$6 and semiconduct\$6 and channel same layer\$6 and source\$6 same electrode\$1 and drain \$6 same electrode\$1 and pad\$1 and contact \$6	US-PGPUB; USPAT; FPFIS; EPO; JPO; DEFWENT; IBM_TDB	OR	OFF	2008/03/06 15:10
S12	10	thin same film\$6 same transistor\$1 same backplane and polyimide same substrate and passivation	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/06 19:24

S13	4	transistor\$1 same	US-PAGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/06 19:25
S14		thin same film\$6 same transistor\$1 same backplane and passivat \$6 and array\$6 and gate same electrode\$1 and insulat\$6 and semiconduct\$6 and channel and source\$6 same electrode\$1 and drain\$6 same electrode\$1 and pad\$1 and contact\$6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/06 19:26
S15	***************************************	(thin same film\$6 same transistor\$1 or TFT) and backplane and passivat\$6 and array\$6 and gate same electrode\$1 and insulat \$6 and semiconduct\$6 and channel and source \$5 same electrode\$1 and drain\$6 same electrode\$1 and pas\$1	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWBNT; IBM_TDB	OR	OFF	2008/03/06 19:26
S16	**************************************	(thin same film\$6 same transistor\$1 or TFT) and backplane and passivat\$6 and array\$6 and gate same electrode\$1 and insulat \$5 and semiconduct\$6 and channel\$5 and source\$6 same electrode\$1 and drain \$6 same electrode\$1 and drain \$5 and contact \$5 and contact \$6 same electrode\$1 and pad\$1 and contact \$6	US-PGPUB; USPAT; FPRS; EPO; IPO; DERWENT; IBM_TDB	OR	OFF	2008/03/06 19:31

S17	8	transistor\$1 same backplane and array\$6 and gate same	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/06 19:41
S18	7	thin same film\$6 same transistor\$1 same backplane and array\$6 and gate same electrode\$1 and insulat \$6 and semiconduct\$6 and channel same layer \$6 and source\$6 same electrode\$1 and drain \$6 same electrode\$1 and pad\$1 and pod\$1 and pod\$1 and pod\$1 same properties that the same same electrode\$1 and pad\$1 and pod\$1 an	US-PGPUB; USPAT; FPRS; EPO; JPO; DEFWENT; IBM_TDB	OR	OFF	2008/03/06 19:42
S19	105978	thin same film\$6 same transistor\$1 same backplane and deposit \$6 and array\$6 and gate same electrode\$1 and insulat\$6 and semiconduct\$6 and channel same layer\$6 and source\$6 same electrode\$1 and pad\$1 and ontact \$6 and source\$6 same \$6 same electrode\$1 and pad\$1 and contact \$6 and source\$1 and pad\$1 and contact \$6 and psessivat\$6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/06 19:43
S20	4	thin same film\$6 same transistor\$1 same backplane and deposit \$6 and array\$6 and gate same electrode\$1 and insulat\$6 and semiconduct\$6 and channel same layer\$6 and source\$6 same electrode\$1 and drain \$6 same electrode\$1 and drain \$6 same electrode\$1 and ontact \$6 and pad\$1 and contact \$6 and psosivat\$6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/06 19:44

S21	4	thin same film\$6 same transistor\$1 same backplane and deposit \$6 and array\$6 and gate same electrode\$1 and insulat\$6 and semiconduct\$6 and channel same layer\$6 and source\$6 same electrode\$1 and frain \$6 same electrode\$1 and nad\$1 and contact \$6 and passiv\$6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/06 19:49
S22	30	thin same film\$6 same transistor\$1 and backplane and deposit \$6 and array\$6 and gate same electrode\$1 and insulat\$6 and semiconduct\$6 and channel same layer\$6 and source\$6 same electrode\$1 and frain \$6 same electrode\$1 and drain and pad\$1 and contact \$6 and passiv\$6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/06 19:50
S23	31	thin same film\$6 same transistor\$1 and backplane and array\$6 and gate same electrode\$1 and insulat \$6 and semiconduct\$6 and channel same layer \$6 and source\$6 same electrode\$1 and drain \$6 same electrode\$1 and pad\$1 and contact \$6 and passiv\$6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/06 19:51
S24	16	thin same film\$6 same transistor\$1 and backplane and array\$6 and gate same electrode\$1 and insulat \$6 and semiconduct\$6 and channel same layer \$6 and source\$6 same electrode\$1 and drain \$6 same electrode\$1 and pad\$1 and contact \$6 and passiv\$6 same layer\$6.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/06 19:58

S25	1056957	input same device and tact\$6 and joystick force sens\$6 same resist\$6 and X same Y same plane\$6 and flex \$6 and plung\$6 same coupl\$6 and dome\$6	USPAT	OR	OFF	2008/03/07 06:43
S26	4	input same device and tact\$6 and joystick and force\$6 and sens\$6 same resist\$6 and X same Y same plane\$6 and flex\$6 and plung \$6 same coupl\$6 and dome\$6	USPAT	OR	OFF	2008/03/07 06:44
S27	4	input same device and tact\$6 and joystick and force\$6 and sens\$6 same resist\$6 and X same Y same plane\$6 and flex\$6 and plung \$6 same coupl\$6 and dome\$6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/07 06:44
S28	2888	(438/149.ccls. or 257/72.ccls.)	USPAT	OR	OFF	2008/03/09 10:21
S2 9	2013	(438/149.ccls. or 257/72.ccls.) and TFT	USPAT	OR	OFF	2008/03/09 10:21
S30	2352	(438/149.ccls. or 257/72.ccls.) and (TFT or thin\$6 same film\$6 same transistor\$1)	USPAT	OR	OFF	2008/03/09 10:22
S31	21	(438/149.ccls. or 257/72.ccls.) and (TFT or thin\$6 same film\$6 same transistor\$1) and backplane	USPAT	OR	OFF	2008/03/09 10:22
S32	5	(438/149.cds. or 257/72.cds.) and (TFT or thin\$6 same film\$6 same transistor\$1) and backplane and passive \$6	USPAT	OR	OFF	2008/03/09 10:22
S33	12	(438/149.cds. or 257/72.cds.) and (TFT or thin\$6 same film\$6 same transistor\$1) and backplane and passive \$6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/09 10:23

S34	0	(438/149.cds. or 257/72.cds.) and (TFT or thin\$6 same film\$6 same transistor\$1) and backplane and passive \$6 and polymide\$6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/09 10:26
S35	9	(438/149.ccls. or 257/72.ccls.) and (TFT or thin\$6 same film\$6 same transistor\$1) and backplane and passive \$6 and polyimide\$6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/09 10:26
S36	9	(438/149.ccls. or 257/72.ccls.) and (TFT or thin\$6 same film\$6 same transistor\$1) and backplane and (passive \$6 and layer\$6) and polyimide\$6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/09 10:36
S37	2	(438/149.ccls. or 257/72.ccls.) and (TFT or thin\$6 same film\$6 same transistor\$1) and backplane and (passive \$6 same layer\$6) and polyimide\$6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/09 10:50
S38	42	("498"/\$.ccls. or "257"/ \$.ccls.) and (TFT or thin\$6 same film\$6 same transistor\$1) and backplane and (passive \$6 same layer\$6) and polyimide\$6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/09 10:52
S39	0	("438"/\$.ccls. or "257"/ \$.ccls.) and (TFT or thin\$6 same film\$6 same transistor\$1) and backplane and (passive \$6 adj layer\$6) and polyimide\$6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/09 10:52
S40	0	("438"/\$.ccls. or "257"/ \$.ccls.) and (TFT or thin\$6 same film\$6 same transistor\$1) and backplane and (passive \$6 adj layer\$6)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/09 10:52
S41	37	("438"/\$.ccls. or "257"/ \$.ccls.) and (TFT or thin\$6 same film\$6 same transistor\$1) and (passive\$6 adj layer\$6)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/09 10:53

S42	3	("438"/\$.ccls. or "257"/ \$.ccls.) and (TFT or thin\$6 same film\$6 same transistor\$1) and (passive\$6 adj layer\$6) and polyimide same substrate\$1	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/09
S43	O	("438"/\$.cols. or "257"/ \$.cols.) and (TFT or thin\$6 same film\$6 same transistor\$1) and (passive\$6 adj layer\$6) and polyimide same substrate\$1 and backplane	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/09 10:57
S44	128	("438"/\$.ccis. or "257"/ \$.ccis.) and (TFT or thin\$6 same film\$6 same transistor\$1) and polyimide same substrate\$1 and backplane	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/09
S45	27	("438"/\$.ccls. or "257"/ \$.cds.) and (TFT or thin\$6 same film\$6 same transistor\$1) and polyimide same substrate\$1 and backplane and array\$6 and gate same electrode\$1 and insulat \$6 and semiconduct\$6 and channel same layer \$6 and source\$6 same electrode\$1 and drain \$6 same electrode\$1 and pad\$1 and contact \$6	US PGPUB; USPAT; FPRS; EPO; JPO; DEFWENT; IBM_TDB	OR	OFF	2008/03/09 10:59
S46	8	("438"/\$.cots. or "257"/ \$.cots.) and (IFT or thin\$6 same film\$6 same transistor\$1) and polyimide same substrate\$1 and backplane and array\$6 and gate same electrode\$1 and insulat \$6 and semicondud\$6 and channel same layer \$6 and source\$6 same electrode\$1 and drain \$6 same electrode\$1 and pad\$1 and contac \$6 and passivation	US-PGPUB; USPAT; FPRS; EPC; JPO; DEFWENT; IBM_TDB	OR	OFF	2008/03/09

S47	1002	("438"/\$.ccls. or "257"/ \$.ccls.) and (TFT or thin\$6 same film\$6 same transitor\$1) and (passivation same layer \$6) and polyimide same substrate\$1	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/09 11:01
S48	13	("438"/\$.ccls. or "257"/ \$.ccls.) and (TFT or thin\$6 same film\$6 same transistor\$1) and (passivation same layer \$6) and polyimide same substrate\$1 and backplane	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/09 11:02
S49	355	thin same film\$6 same transistor\$1 and backplane and array\$6 and gate same electrode\$1 and insulat \$6 and semiconduct\$6 and channel same layer \$6 and source\$6 same electrode\$1 and drain \$6 same electrode\$1 and oontact \$6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/09 11:26
S50	**************************************	(thin same film\$6 same transistor\$1 or IFF) same (substrate same backplane) and backplane and array\$6 and gate same electrode\$1 and insulat \$6 and semiconduct\$6 and channel same layer \$6 and source\$6 same electrode\$1 and drain \$6 same electrode\$1 and drain \$6 same electrode\$1 and drain \$6 same alectrode\$1 and contact \$6	US-PGPUB; USPAT; FPFS; EPC; JPC; DERWENT; IBM_TDB	OR	OFF	2008/03/09
S51	36	("438"/\$.ccls. or "257"/ \$.ccls.) and (TFT or thin\$6 same flim\$6 same transistor\$1) and backplane and (passive \$6 same layer\$6) and polyimide\$6 same substrate\$1	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/09 11:56

S52	18		USPAT; FPRS; EPO; JPO;	OR	OFF	2008/03/09 11:57
S53	0	"20030108664"	USPAT	OR	OFF	2008/03/09 12:18
S54	3	"20030108664"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/09 12:18
S55	0	"20030108664" and contact same pad\$6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/09 12:19
S56	0	"20040180476" and contact\$6 same pad\$6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/09 12:21

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